Power MOSFET

-20 V, -9.4 A, μCool™ Single P-Channel, ESD, 2.0x2.0x0.65 mm UDFN Package

Features

- UDFN Package with Exposed Drain Pads for Excellent Thermal Conduction
- Low Profile UDFN 2.0x2.0x0.65 mm for Board Space Saving
- Lowest RDS(on) in 2.0x2.0 Package
- ESD Protected
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

Applications

- High Side Load Switch
- PA Switch and Battery Switch
- Optimized for Power Management Applications for Portable Products, such as Cell Phones, PMP, DSC, GPS, and others

MAXIMUM RATINGS ($T_J = 25^{\circ}C$ unless otherwise stated)

Parameter			Symbol	Value	Units
Drain-to-Source Voltage			V_{DSS}	-20	V
Gate-to-Source Voltage			V_{GS}	±8.0	V
Continuous Drain	Steady State	T _A = 25°C	I _D	-6.4	Α
Current (Note 1)		T _A = 85°C		-4.6	
	t ≤ 5 s	T _A = 25°C		-9.4	
Power Dissipa- tion (Note 1)	Steady State	T _A = 25°C	P _D	1.7	W
	t ≤ 5 s	T _A = 25°C		3.8	
Continuous Drain	Steady State	T _A = 25°C	I _D	-4.0	Α
Current (Note 2)		T _A = 85°C		-2.9	
Power Dissipation (Note 2) T _A = 25°C		P_{D}	0.7	W	
Pulsed Drain Current tp = 10 μs		I _{DM}	-30	Α	
Operating Junction and Storage Temperature			T _J , T _{STG}	-55 to 150	°C
Source Current (Body Diode) (Note 2)			I _S	-1.0	Α
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)		T _L	260	°C	
ESD Rating (HBM) per JESD22-A114F			ESD	>2000	V

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

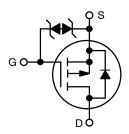
- Surface Mounted on FR4 Board using 1 in sq pad size (Cu area = 1.127 in sq [2 oz] including traces).
- Surface-mounted on FR4 board using the minimum recommended pad size of 30 mm², 2 oz. Cu.



ON Semiconductor®

http://onsemi.com

MOSFET				
V _{(BR)DSS}	R _{DS(on)} MAX	I _D MAX		
-20 V	29 mΩ @ -4.5 V			
	39 mΩ @ –2.5 V	_9.4 A		
	60 mΩ @ -1.8 V			
	120 mQ @ -1.5 V			



P-Channel MOSFET

MARKING DIAGRAM



UDFN6 CASE 517BG μCOOL™



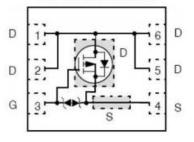
AA = Specific Device Code

M = Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

PIN CONNECTIONS



(Top View)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

1

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Max	Units
Junction-to-Ambient - Steady State (Note 3)	$R_{\theta JA}$	72	°C/W
Junction-to-Ambient − t ≤ 5 s (Note 3)	$R_{\theta JA}$	33	
Junction-to-Ambient - Steady State min Pad (Note 4)	$R_{\theta JA}$	189	

ELECTRICAL CHARACTERISTICS	S (T _J = 25 $^{\circ}$ C unles	s otherwise specifie	d)				
Parameter	Symbol	Test Condition		Min	Тур	Max	Units
OFF CHARACTERISTICS							
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$		-20			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	$V_{(BR)DSS}/T_J$	$I_D = -250 \mu A$, ref to 25°C			-5.0		mV/°C
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V, V _{DS} = -20 V	$T_{J} = 25^{\circ}C$ $T_{J} = 85^{\circ}C$			-1.0 -10	μΑ
Gate-to-Source Leakage Current	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8.0 \text{ V}$				±10	μΑ
ON CHARACTERISTICS (Note 5)	433	D3 ,	45		<u> </u>		Par 1
Gate Threshold Voltage	V _{GS(TH)}	VGS = VDS.	I _D = -250 μA	-0.4		-1.0	V
Negative Threshold Temp. Coefficient	V _{GS(TH)} /T _J	GG DG ⁷	<i>V</i>		3.0		mV/°C
Drain-to-Source On Resistance	R _{DS(on)}	$V_{GS} = -4.5 \text{ V}, I_D = -6.4 \text{ A}$			23	29	mΩ
	==(=:-)		V, I _D = -4.8 A		31	39	
			V, I _D = -2.5 A		43	60	
			V, I _D = -1.5 A		60	120	
Forward Transconductance	g _{FS}	V _{DS} = -15 \	/, I _D = −4.0 A		18		S
CHARGES, CAPACITANCES & GATE	RESISTANCE				<u>!</u>		
Input Capacitance	C _{ISS}	$V_{GS} = 0 \text{ V, } f = 1 \text{ MHz,} $ $V_{DS} = -15 \text{ V}$			2600		pF
Output Capacitance	C _{OSS}				200		1
Reverse Transfer Capacitance	C _{RSS}				190		
Total Gate Charge	Q _{G(TOT)}	$V_{GS} = -4.5 \text{ V}, V_{DS} = -15 \text{ V};$ $I_{D} = -4.0 \text{ A}$			29		nC
Threshold Gate Charge	Q _{G(TH)}				1.4		1
Gate-to-Source Charge	Q _{GS}				3.7		
Gate-to-Drain Charge	Q_{GD}				8.1		
SWITCHING CHARACTERISTICS, VG	S = 4.5 V (Note 6)						
Turn-On Delay Time	t _{d(ON)}				9.0		ns
Rise Time	t _r	$V_{GS} = -4.5 \text{ V}, V_{DD} = -15 \text{ V},$			18		
Turn-Off Delay Time	t _{d(OFF)}	$I_{\rm D} = -4.0 A$	$A, R_G = 1 \Omega$		126		
Fall Time	t _f				71		
DRAIN-SOURCE DIODE CHARACTER	ISTICS						
Forward Diode Voltage	VSD	V _{GS} = 0 V,	T _J = 25°C		0.65	1.0	V
		$I_S = -1.0 \text{ A}$ $T_J = 125^{\circ}\text{C}$		0.55			
Reverse Recovery Time	t _{RR}	$V_{GS} = 0 \text{ V, dis/dt} = 100 \text{ A/}\mu\text{s,}$ $I_{S} = -1.0 \text{ A}$			25		ns
Charge Time	t _a				10		
Discharge Time	t _b				15		
Reverse Recovery Charge	Q _{RR}				13.6		nC

- Surface-mounted on FR4 board using 1 in sq pad size (Cu area = 1.127 in sq [2 oz] including traces).
 Surface-mounted on FR4 board using the minimum recommended pad size of 30 mm², 2 oz. Cu.
 Pulse Test: pulse width ≤ 300 μs, duty cycle ≤ 2%.

- 6. Switching characteristics are independent of operating junction temperatures.

TYPICAL CHARACTERISTICS

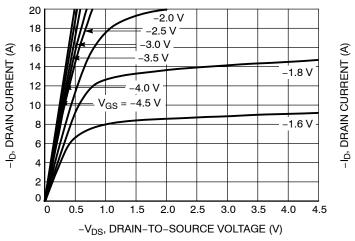


Figure 1. On–Region Characteristics

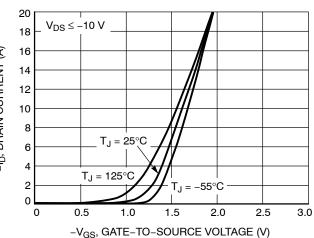


Figure 2. Transfer Characteristics

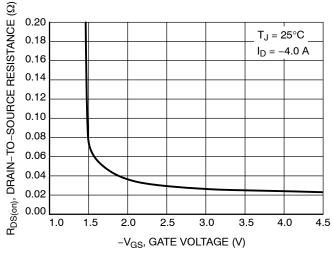


Figure 3. On-Resistance vs. Gate-to-Source Voltage

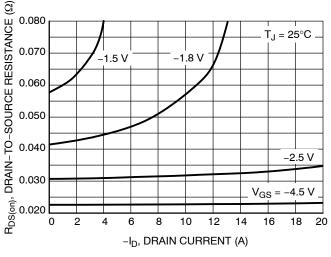


Figure 4. On-Resistance vs. Drain Current and Gate Voltage

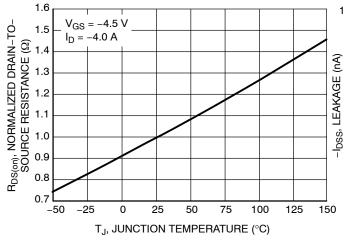


Figure 5. On–Resistance Variation with Temperature

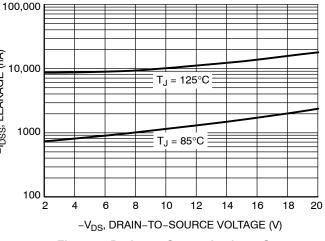


Figure 6. Drain-to-Source Leakage Current vs. Voltage

TYPICAL CHARACTERISTICS

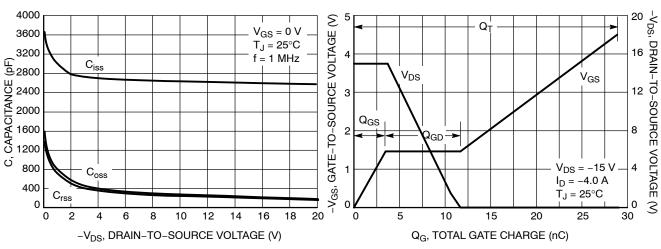


Figure 7. Capacitance Variation

Figure 8. Gate-to-Source and Drain-to-Source Voltage vs. Total Charge

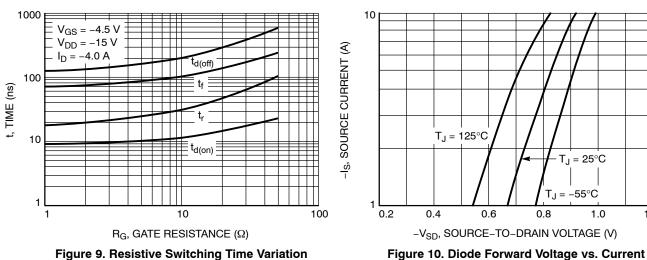


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

1.2

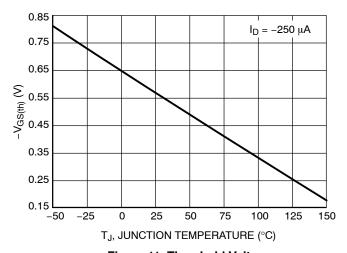


Figure 11. Threshold Voltage

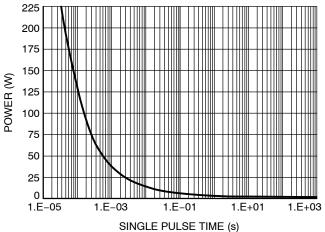


Figure 12. Single Pulse Maximum Power Dissipation

TYPICAL CHARACTERISTICS

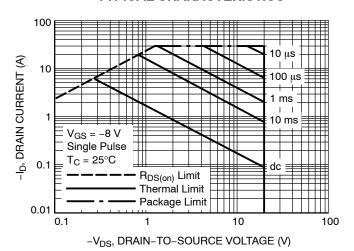


Figure 13. Maximum Rated Forward Biased Safe Operating Area

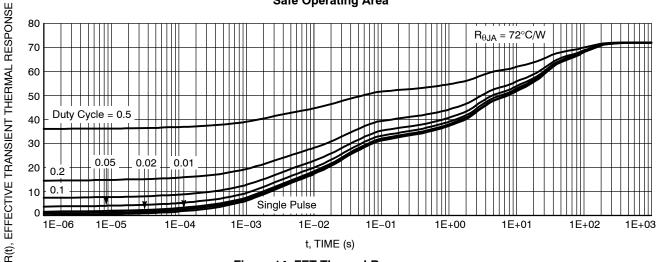


Figure 14. FET Thermal Response

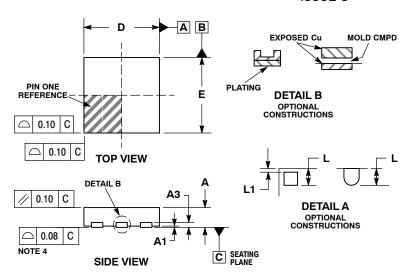
DEVICE ORDERING INFORMATION

Device	Package	Shipping [†]
NTLUS3A40PZTAG	UDFN6 (Pb-Free)	3000 / Tape & Reel
NTLUS3A40PZTBG	UDFN6 (Pb-Free)	3000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

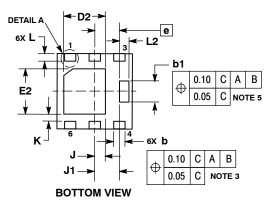
UDFN6 2x2, 0.65P CASE 517BG-01 **ISSUE O**



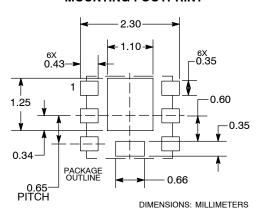
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: MILLIMETERS.
 DIMENSION b APPLIES TO PLATED TERMINAL AND IS
- MEASURED BETWEEN 0.15 AND 0.30 mm FROM TERMINAL COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS
- CENTER TERMINAL LEAD IS OPTIONAL CENTER TERMINAL
- IS CONNECTED TO TERMINAL LEAD # 4.

 6. LEADS 1, 2, 5 AND 6 ARE TIED TO THE FLAG.

	ELITED 1, E, OTHER OTHER THE						
ſ		MILLIMETERS					
	DIM	MIN	MAX				
	Α	0.45	0.55				
	A1	0.00	0.05				
	A3	0.13 REF					
	b	0.25	0.35				
	b1	0.51	0.61				
Γ	D	2.00 BSC					
Γ	D2	1.00	1.20				
Ι	E	2.00 BSC					
	E2	1.10	1.30				
	е	0.65 BSC					
	K	0.15 REF					
	J	0.27 BSC					
	J1	0.65 BSC					
L	L	0.20	0.30				
	L1		0.10				
	L2	0.20	0.30				



RECOMMENDED MOUNTING FOOTPRINT



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